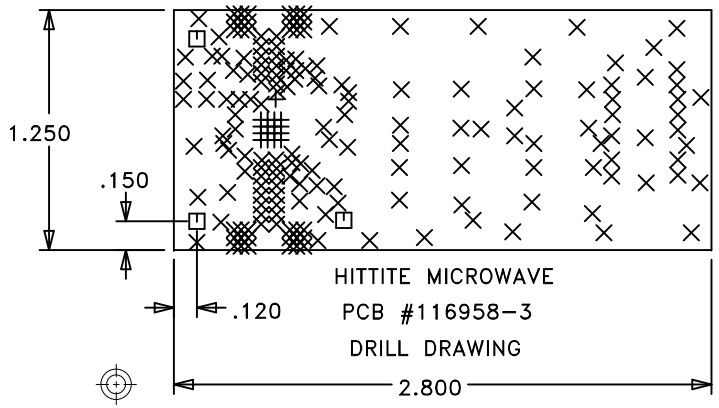
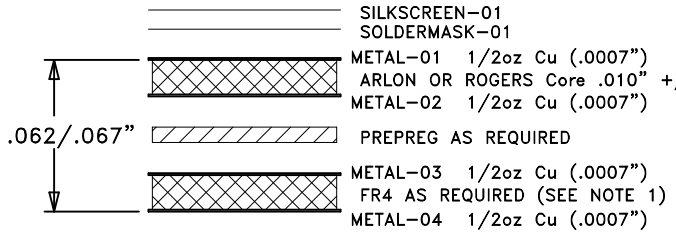
DO NOT SCALE PRINT

REVISION				
ZONE	LTR	DESCRIPTION	DATE	APPROVED
	1	ENGINEERING RELEASE	02/15/07	DMF
	2	REMOVED COMPS BASED ON NEW DESIGN	07/11/07	DMF
	3	UPDATE DIGITAL ATTENUATOR	10/22/09	V. LY



SIZE	QTY	SYM	PLATED	TOL
10	17	+	YES	+/-3
14	176	X	YES	+/-3
43	3	□	YES	+/-3

LAYER	DESCRIPTION
1	RF/GND PLANE
2	GND PLANE
3	SIG/GND PLANE
4	BOTTOM GND PLANE



LAYER STACKUP

NOTES:
UNLESS OTHERWISE SPECIFIED:

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350 OR ARLON 25FR, HALF OUNCE COPPER BOTH SIDES, FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 8 TO 40 MICROINCHES OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ±.003" OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ±.003" MAX.
7. BOARD WARPAGE: <.010" PER LINEAR INCH.
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK.
9. PLATING THICKNESS .002"±.0005 FOR METAL-01 AND METAL-04.
10. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION: ±.004 MAX.
11. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPARATION.
12. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
13. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
14. MANUFACTURE PER IPC-600 CLASS 2.

SPECIAL REQUIREMENTS:

15. METAL-01 CRITICAL LINE WIDTH = .016 ±.001" ADJUST PROCESS TO ACHIEVE WIDTH.

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN INCHES (MM)
DRAWING PRACTICES PER MIL-STD-100
TOLERANCES:

.XX	+/- 0.010
.XXX	+/- 0.005
.XXXX	+/- 0.002
ANGLES	+/- .5 DEG

DWN BY: V. LY 10/21/2009
ENGINEER: K. AYYILDIZ 10/22/2009

HITTITE MICROWAVE CORPORATION
20 Alpha Road Chelmsford, MA 01824

TITLE
PCB, EVAL,
HMC625/HMC627/HMC742LP5E

SIZE	CODE ID NO.	DRAWING NO.	REV
A	1CN88	116958	3

SCALE: | WT | SHEET 1 of 1